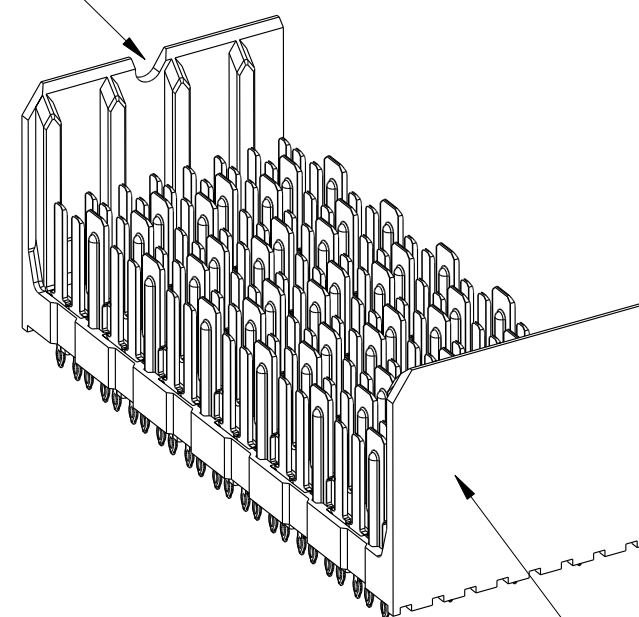
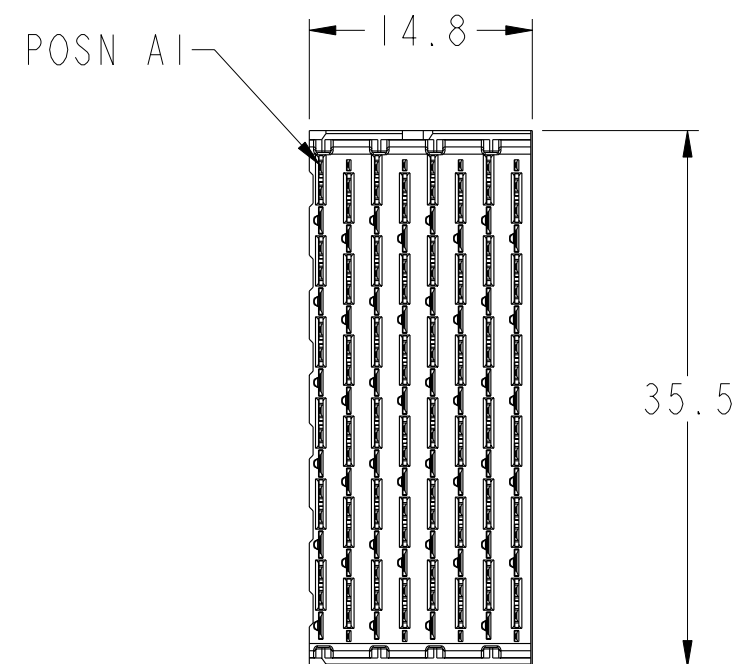


OPEN (2-WALL) MODULE

SEE NOTE 8

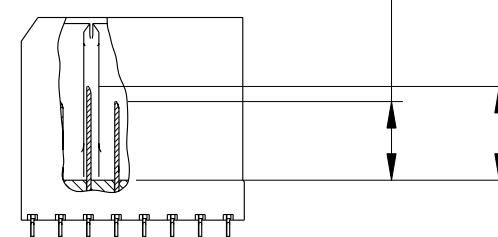


SEE NOTE 5

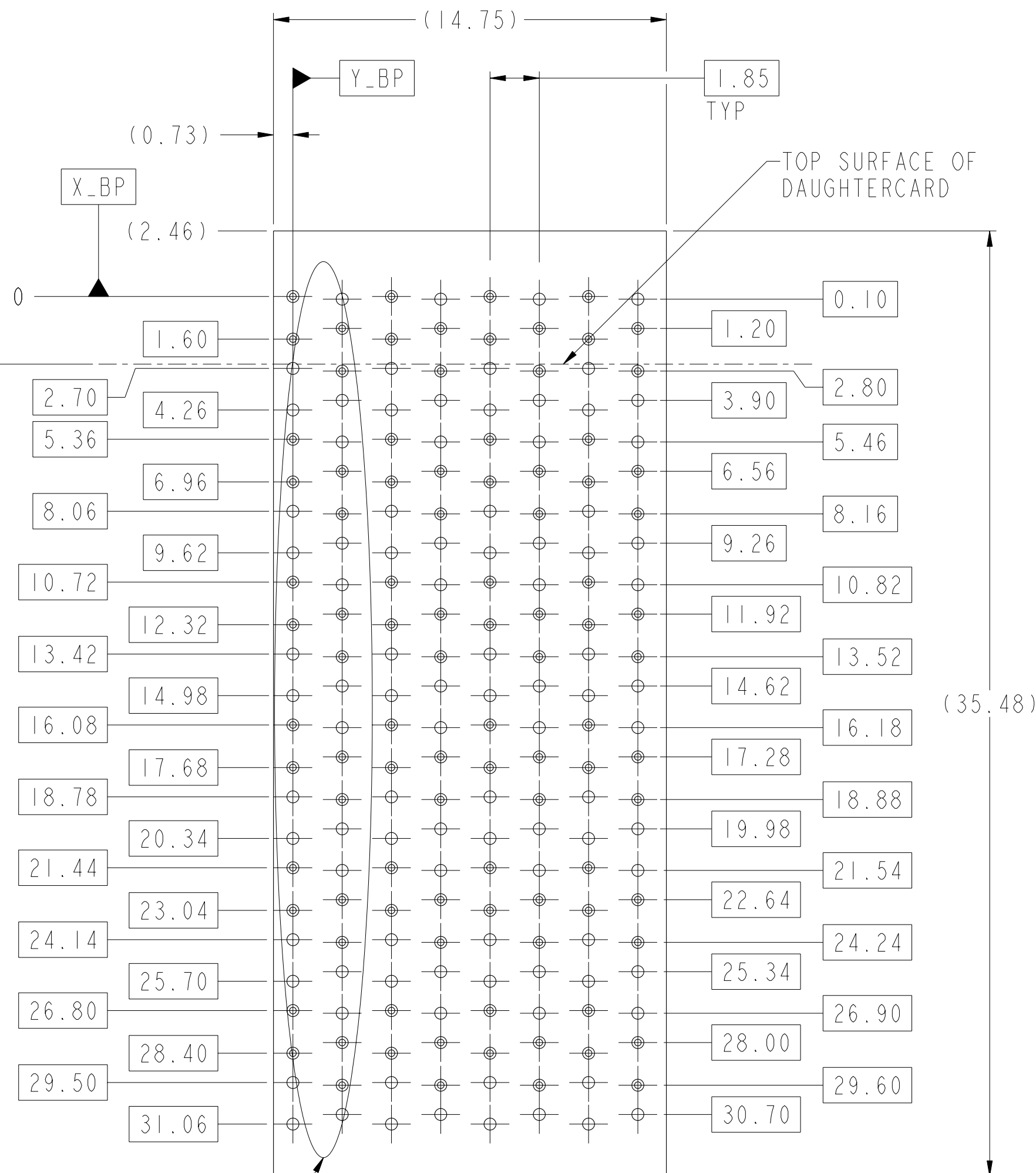


6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

(SEE P/N TREE FOR
ALL COMBINATIONS AVAILABLE)

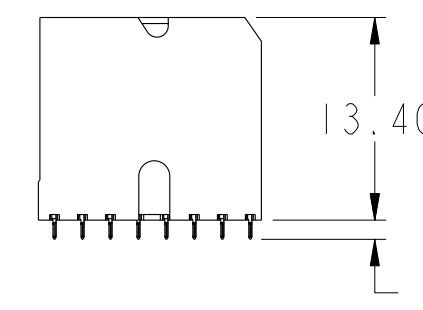
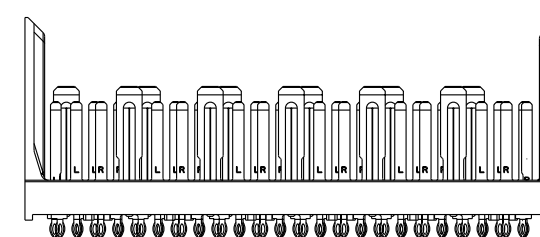


2.54
TO TOP SURFACE
OF DAUGHTERCARD



SEE DETAIL A
(SHEET 8)

PCB HOLE PATTERN
COMPONENT SIDE
SCALE 6:1



PRELIMINARY



title MODULE ASSEMBLY
VERTICAL HEADER, 8-COLUMN, 6-PAIR
catalog no SEE P/N TREE

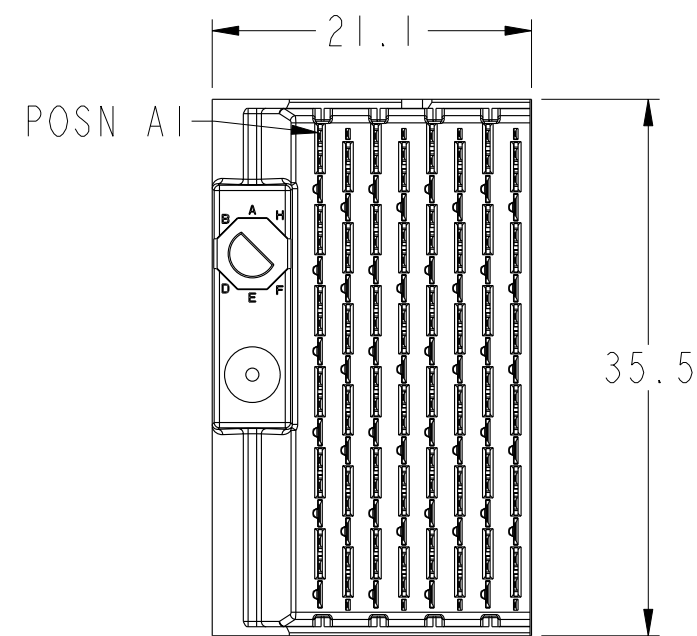
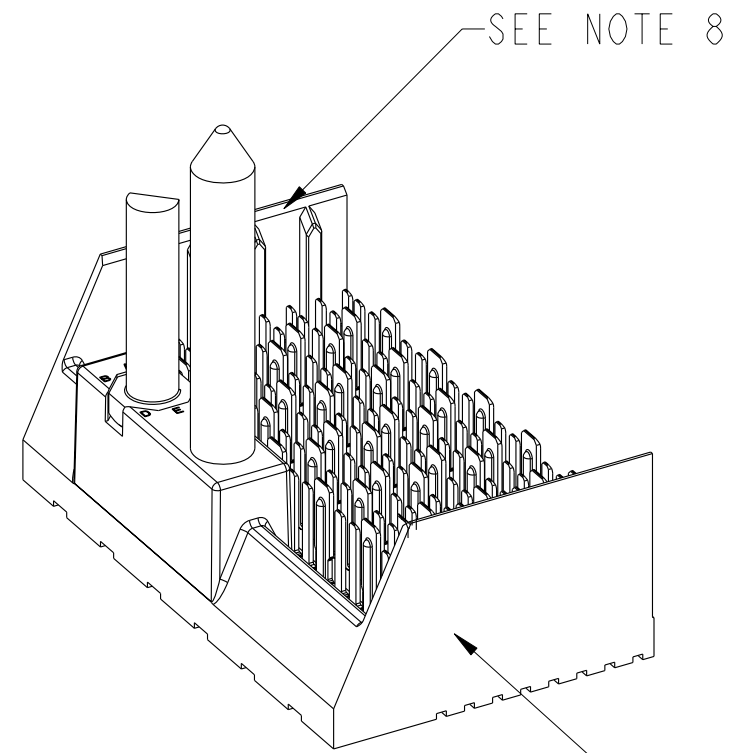
dwg no 10104999
customer sheet 2 of 8

Rev.
2

PDM: Rev:2

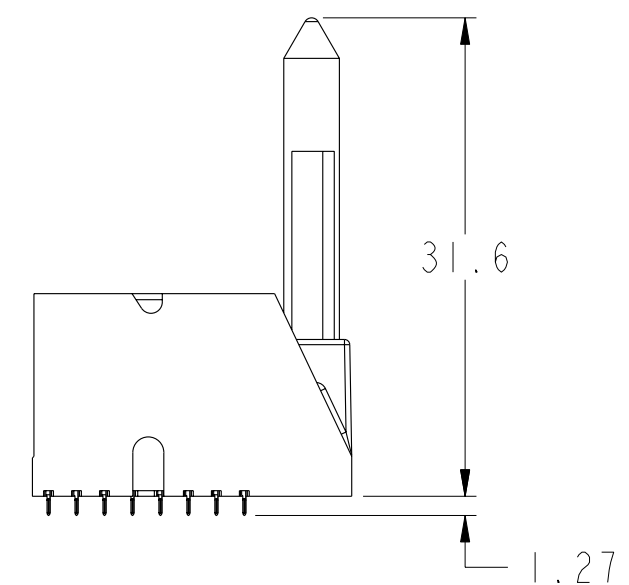
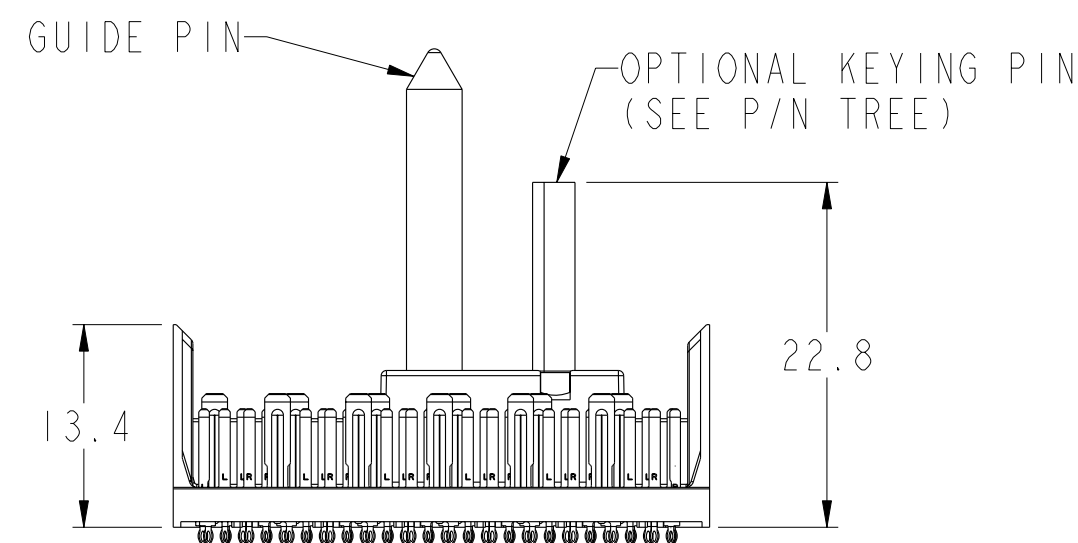
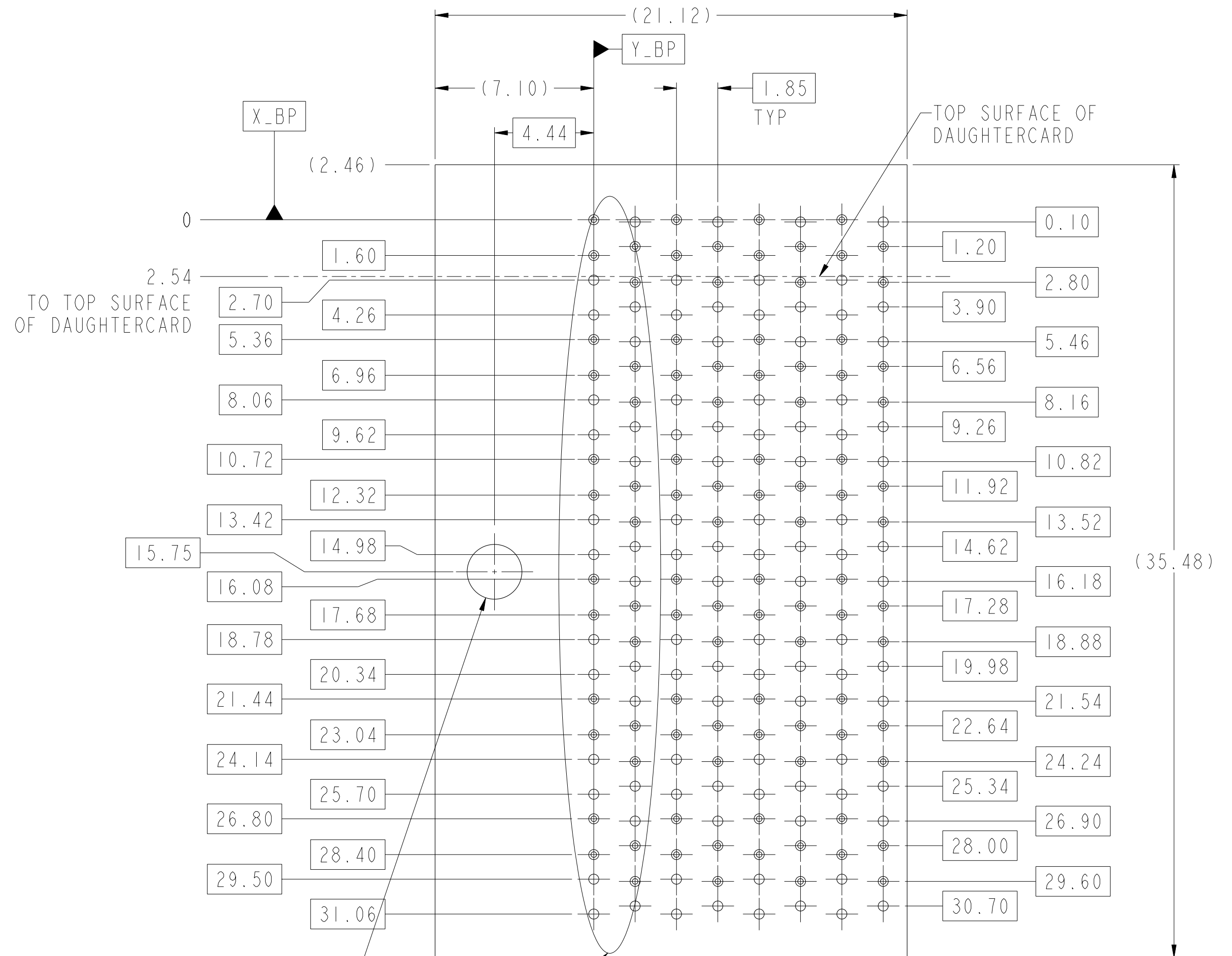
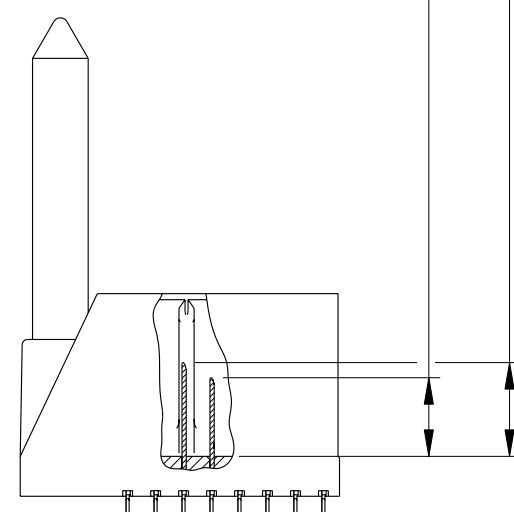
STATUS: In Work 8 Printed: Aug 16, 2010

LEFT POLARIZING/GUIDE MODULE



6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

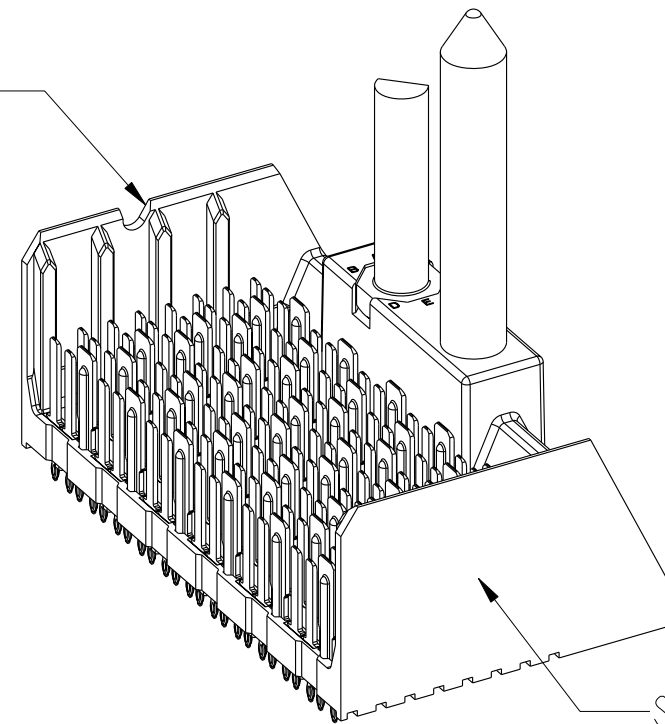
(SEE P/N TREE FOR ALL COMBINATIONS AVAILABLE)



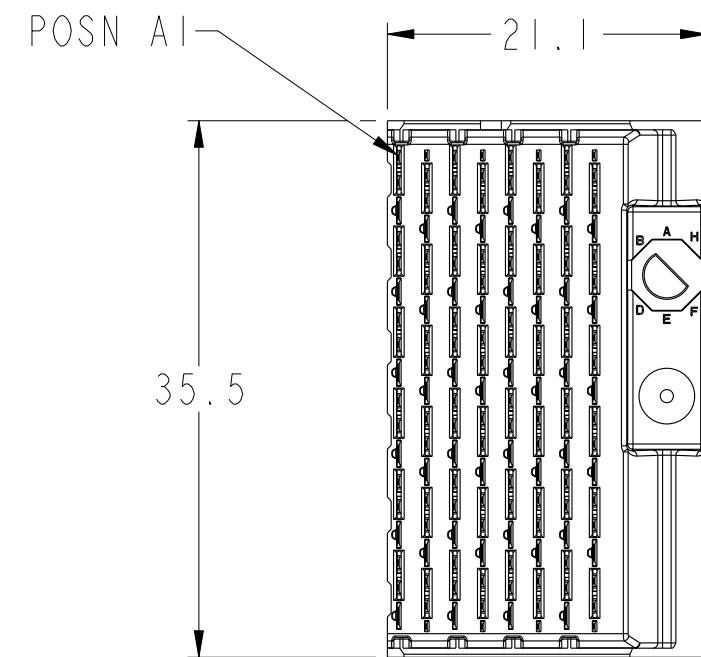
	title		dwg no		Rev.
	MODULE ASSEMBLY		10104999		2
	VERTICAL HEADER, 8-COLUMN, 6-PAIR				
	catalog no	SEE P/N TREE	CUSTOMER	sheet 3 of 8	

RIGHT POLARIZING/GUIDE MODULE

SEE NOTE 8

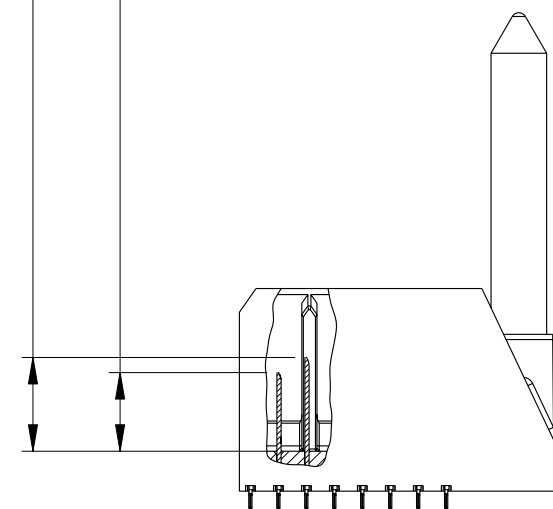


SEE NOTE 5



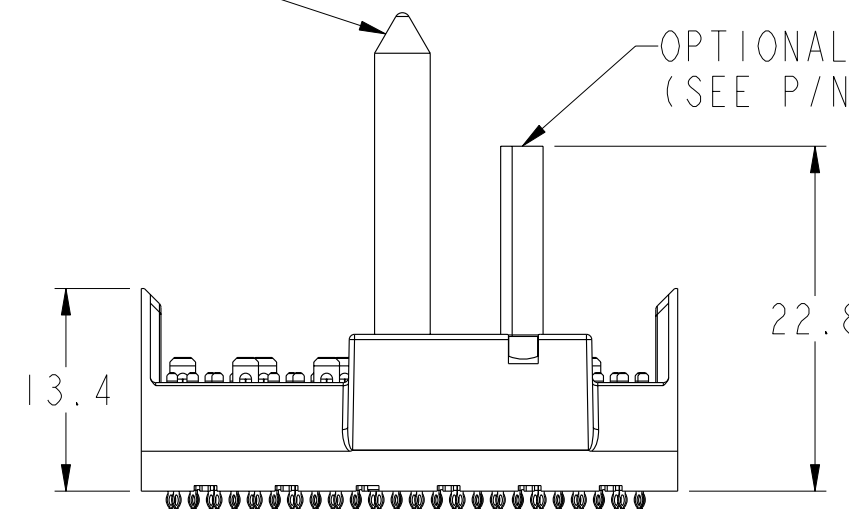
6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

(SEE P/N TREE FOR ALL COMBINATIONS AVAILABLE)

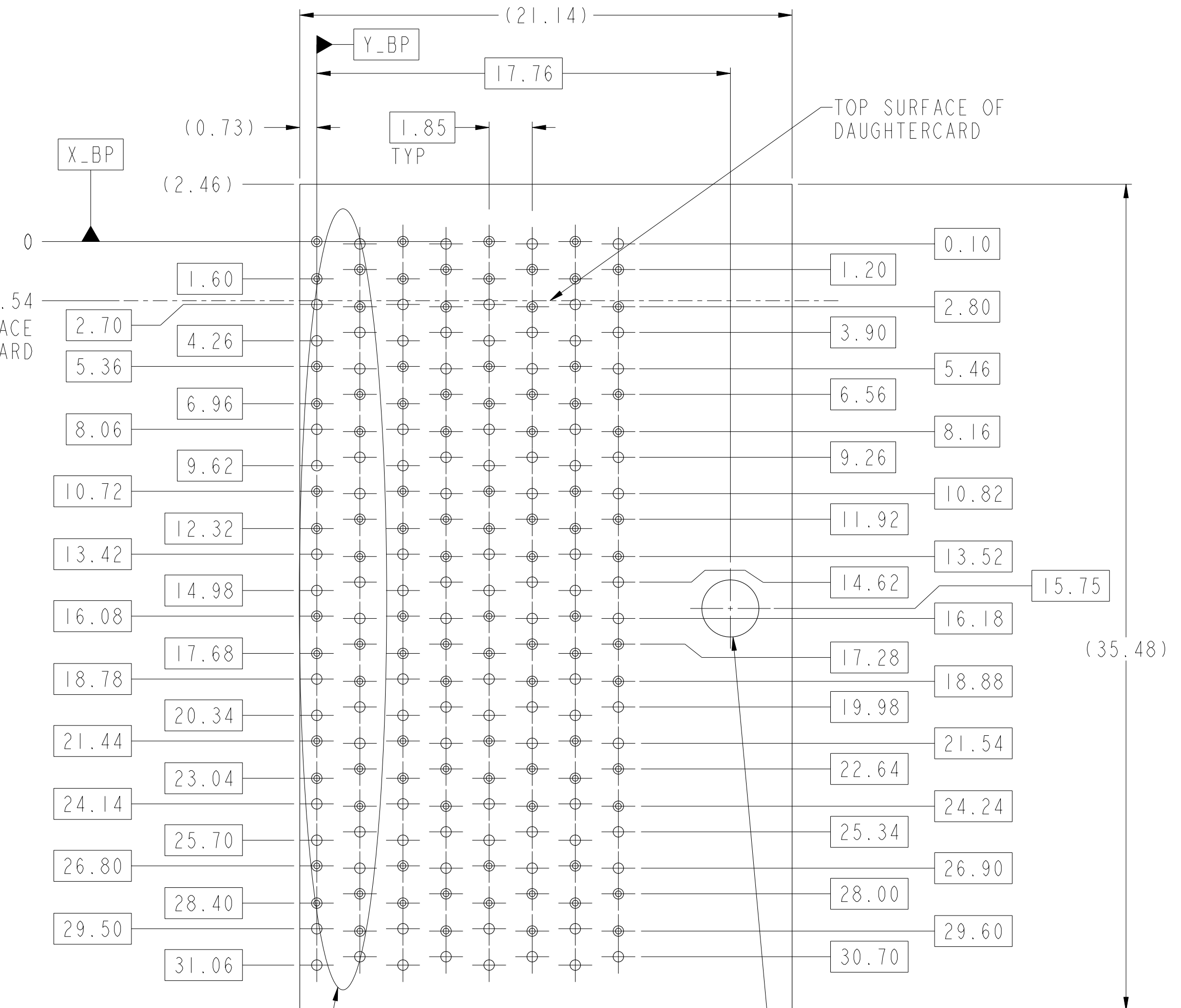


GUIDE PIN

OPTIONAL KEYING PIN
(SEE P/N TREE)



TOP SURFACE OF DAUGHTERCARD



SEE DETAIL A
(SHEET 8)

NOMINAL MODULE OUTLINE
PCB HOLE PATTERN
COMPONENT SIDE
SCALE 6:1

Ø 2.55
2.35
Ø 0.10 A Y_BP X_BP
SEE NOTE 11 & TABLE 1

PRELIMINARY

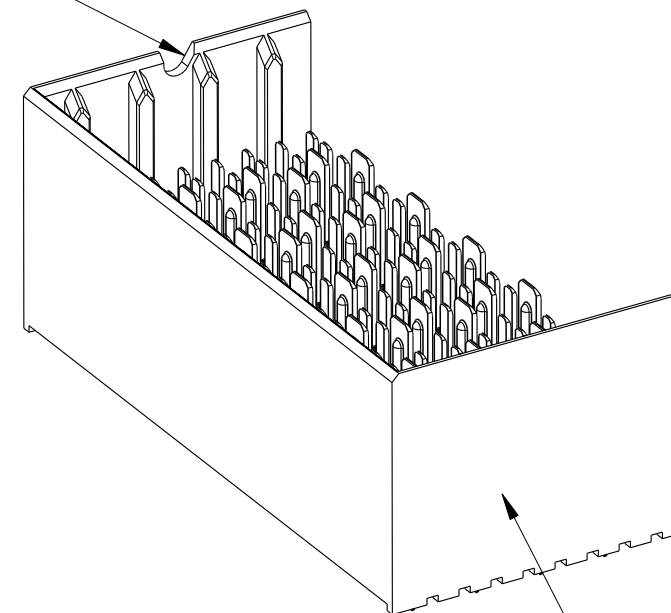


MODULE ASSEMBLY
VERTICAL HEADER, 8-COLUMN, 6-PAIR
SEE P/N TREE

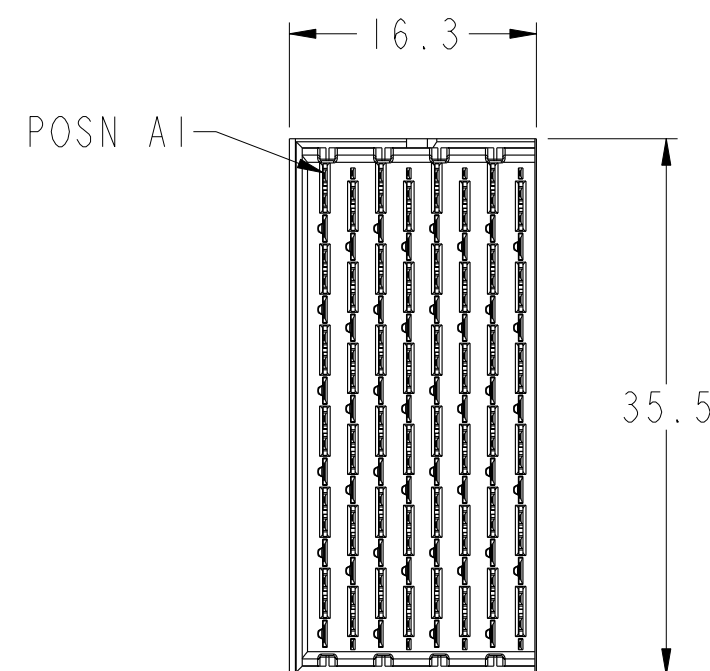
10104999
CUSTOMER
sheet 4 of 8

LEFT WALL MODULE

SEE NOTE 8



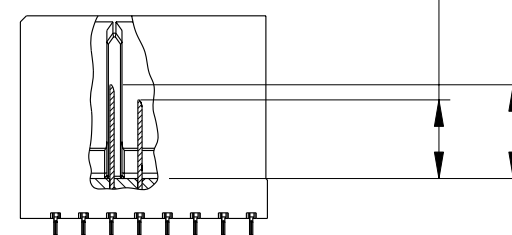
SEE NOTE 5



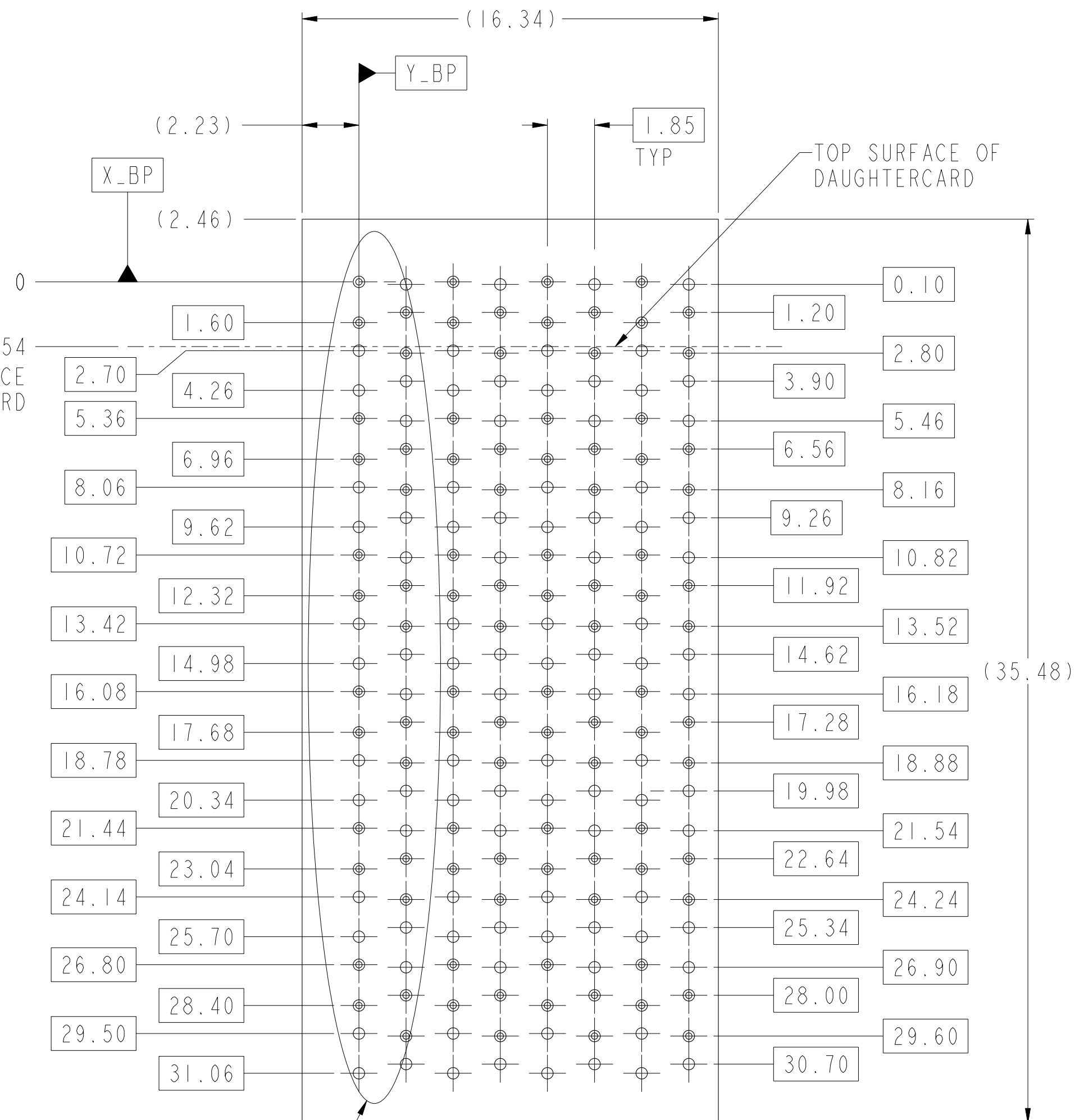
SCALE 2:1

6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

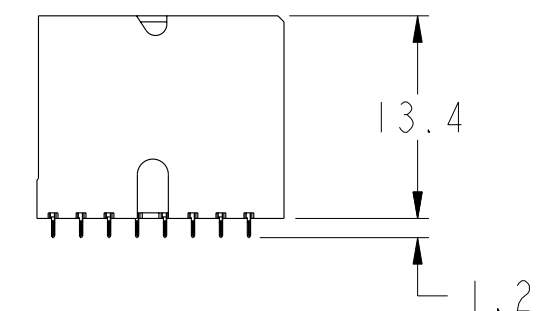
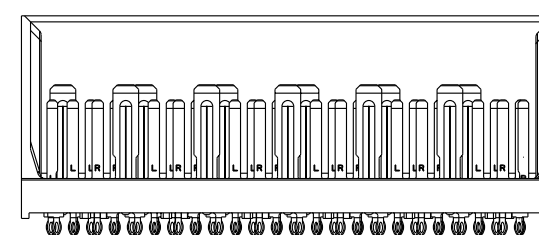
(SEE P/N TREE FOR ALL COMBINATIONS AVAILABLE)



2.54
TO TOP SURFACE
OF DAUGHTERCARD



SEE DETAIL A
(SHEET 8)



PRELIMINARY

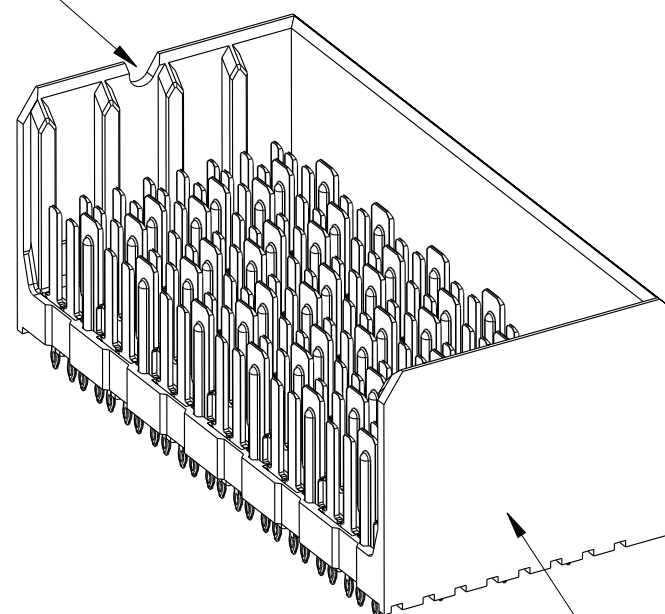


MODULE ASSEMBLY
VERTICAL HEADER, 8-COLUMN, 6-PAIR
SEE P/N TREE

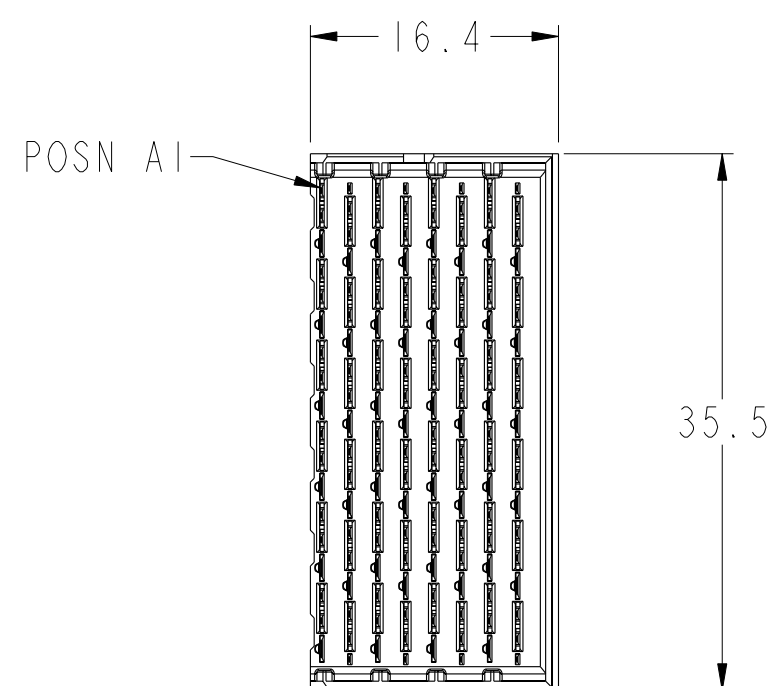
10104999
CUSTOMER
sheet 5 of 8

RIGHT WALL MODULE

SEE NOTE 8



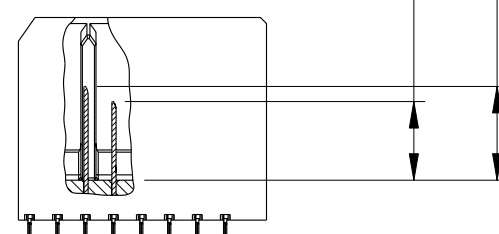
SEE NOTE 5



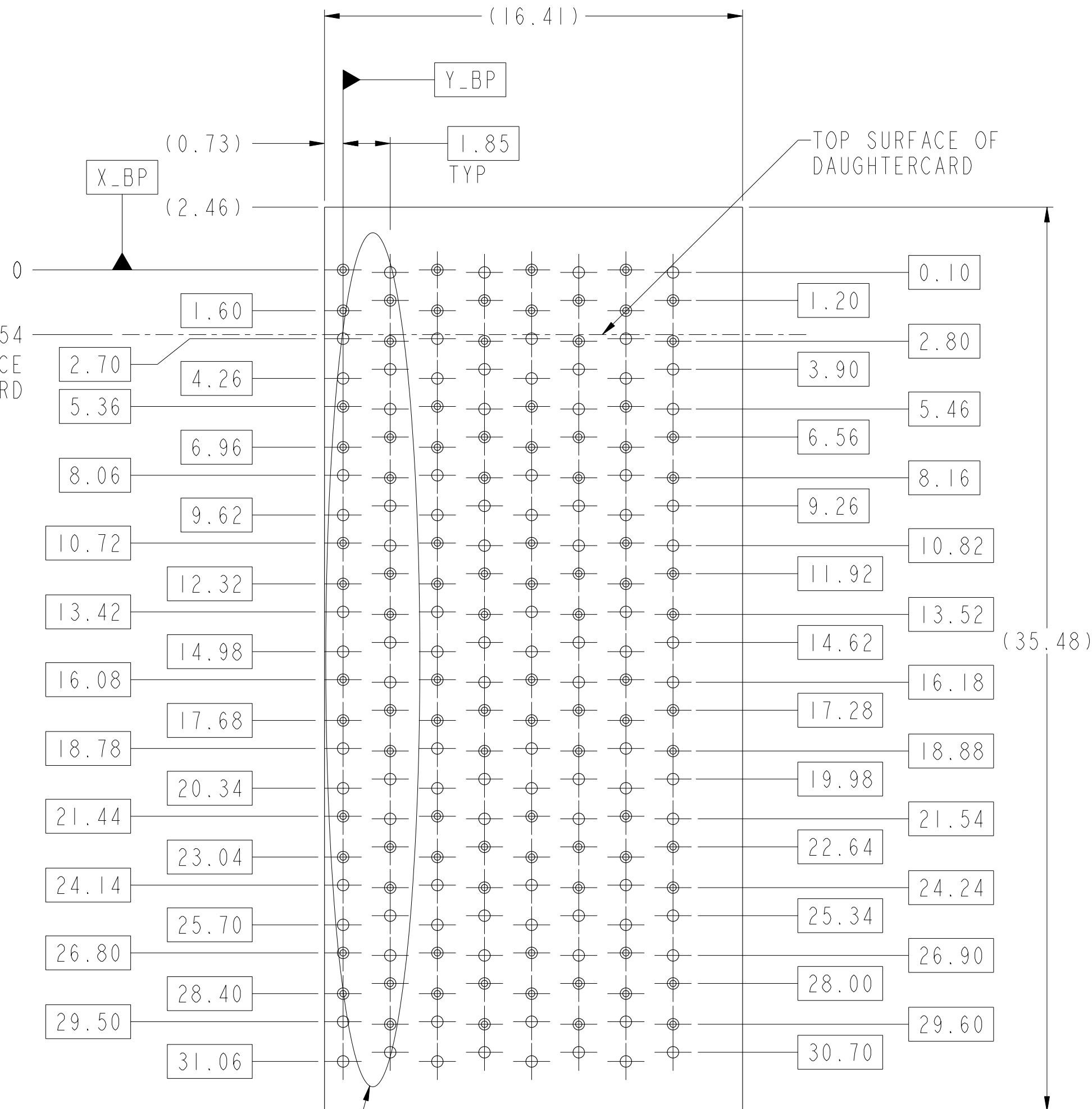
SCALE 2:1

6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

(SEE P/N TREE FOR
ALL COMBINATIONS AVAILABLE)



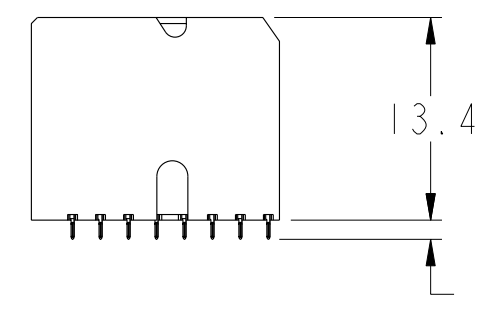
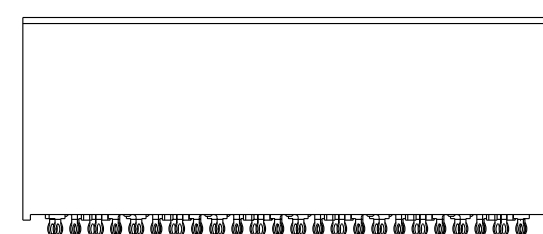
TO TOP SURFACE
OF DAUGHTERCARD



SEE DETAIL A
(SHEET 8)

NOMINAL MODULE OUTLINE

PCB HOLE PATTERN
COMPONENT SIDE
SCALE 6:1



PRELIMINARY



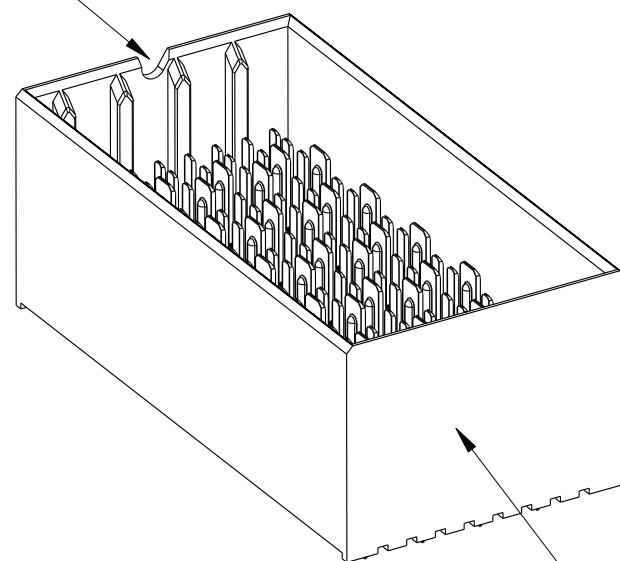
MODULE ASSEMBLY
VERTICAL HEADER, 8-COLUMN, 6-PAIR
SEE P/N TREE

10104999
CUSTOMER
sheet 6 of 8

PDM: Rev:2 STATUS: In Work 8 Printed: Aug 16, 2010

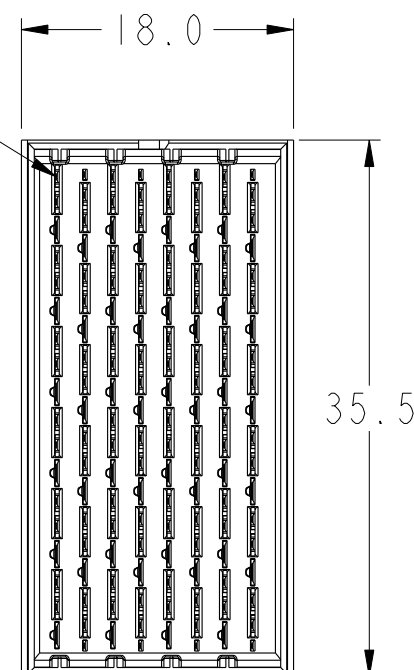
FOUR WALL MODULE

SEE NOTE 8



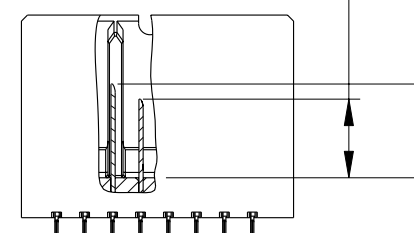
SEE NOTE 5

POSN A1

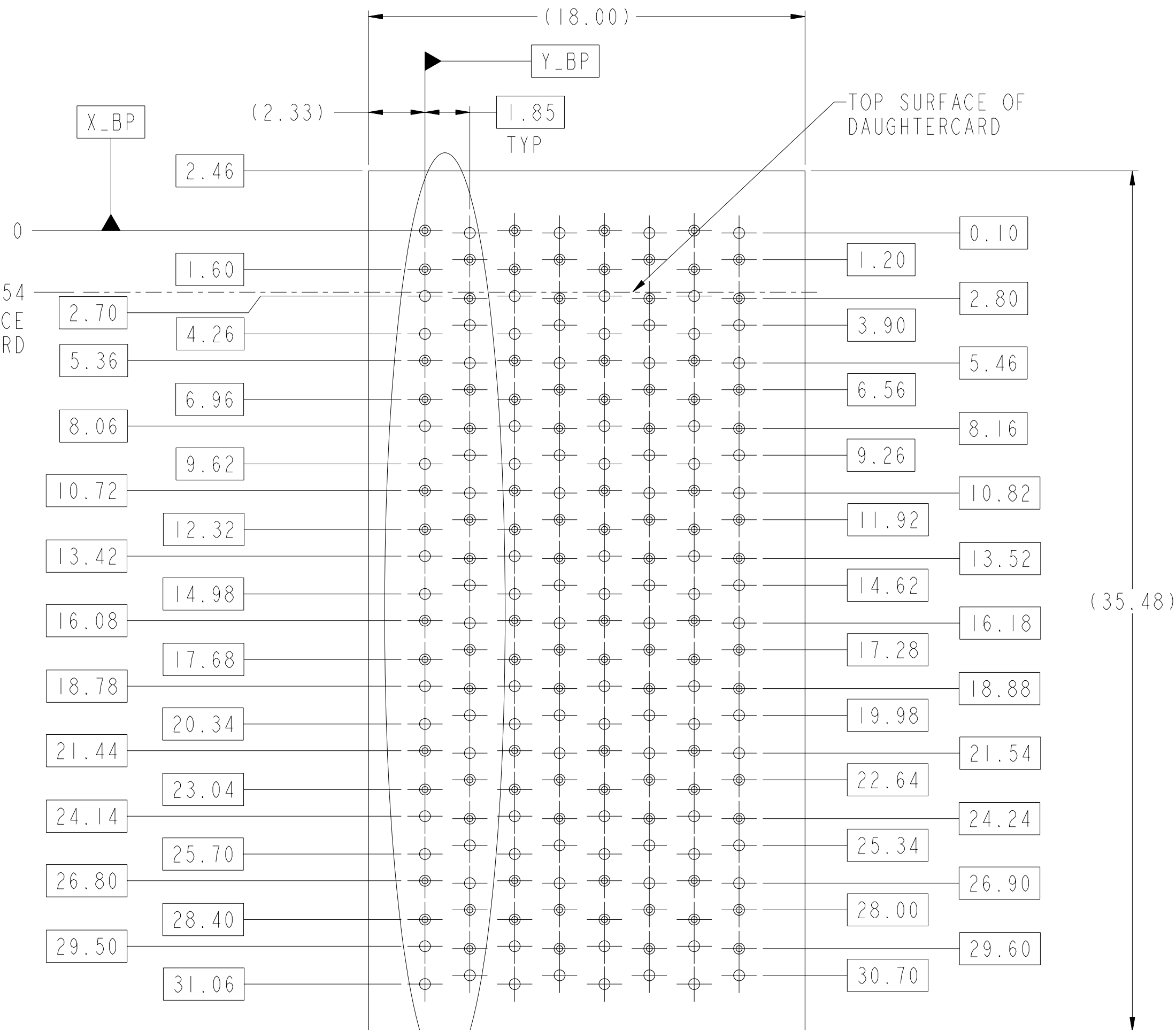


6.2 (4mm WIPE WIDE GROUNDS)
5.2 (3mm WIPE WIDE GROUNDS)
5.2 (THIN END GROUNDS)
5.2 (3mm WIPE SIGNALS)
4.2 (2mm WIPE SIGNALS)

(SEE P/N TREE FOR ALL COMBINATIONS AVAILABLE)



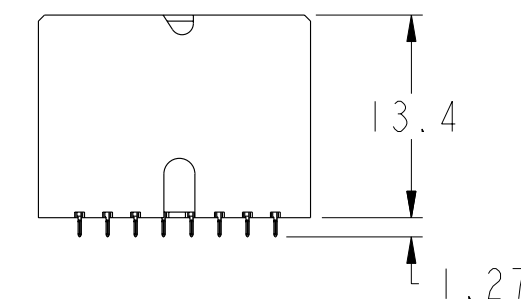
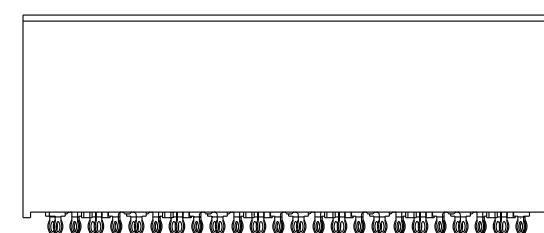
2.54
TO TOP SURFACE
OF DAUGHTERCARD



SEE DETAIL A
(SHEET 8)

PCB HOLE PATTERN
COMPONENT SIDE
SCALE 6:1

NOMINAL MODULE OUTLINE



PRELIMINARY



title MODULE ASSEMBLY
VERTICAL HEADER, 8-COLUMN, 6-PAIR
catalog no SEE P/N TREE

dwg no 10104999
Rev. 2
CUSTOMER sheet 7 of 8

NOTES:

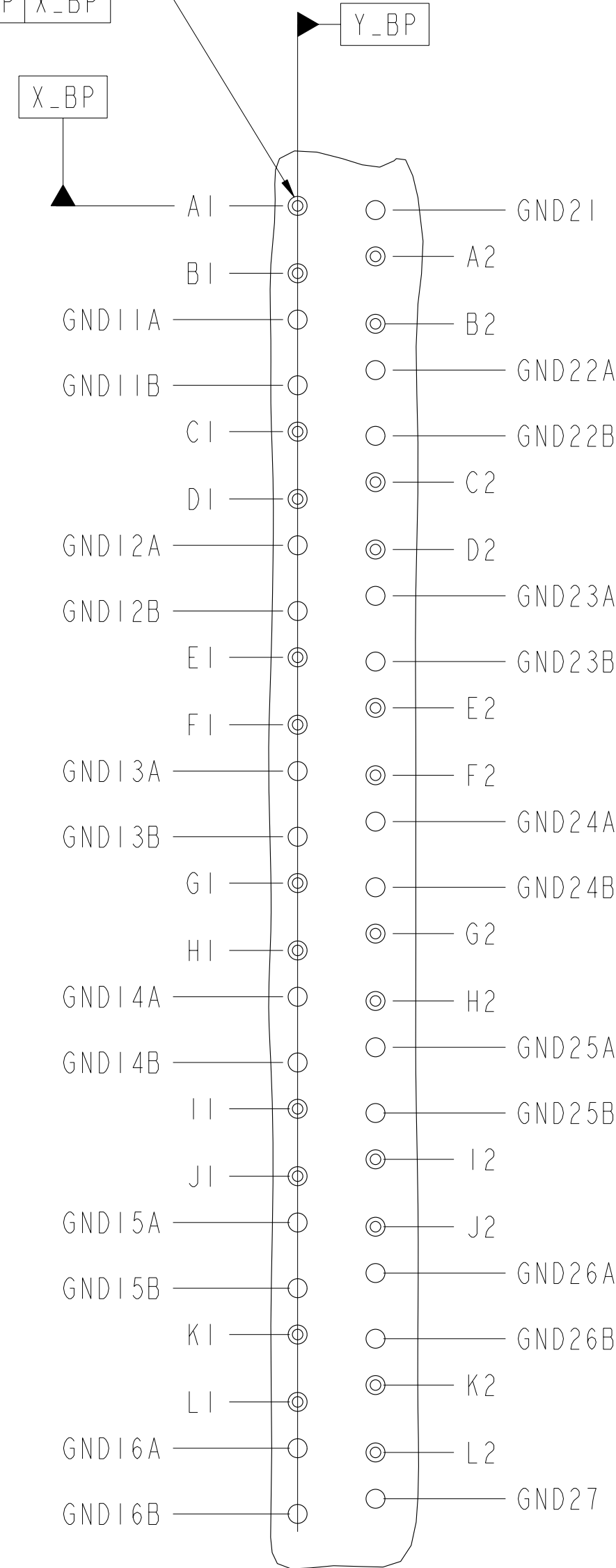
- CONNECTOR MATERIALS
SHROUD: HIGH-TEMP THERMOPLASTIC, UL94V-0
CONTACTS: HIGH PERFORMANCE COPPER ALLOY
- CONTACT PLATING:

SEPARABLE INTERFACE: PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-12-588, INCLUDING TELCORDIA GR-1217-CORE (NOVEMBER 1995) CENTRAL OFFICE TEST SEQUENCE.

PRESS-FIT TAILS: TIN OVER NICKEL, OR TIN-LEAD ALLOY OVER NICKEL. SEE P/N TREE.
- PRODUCT SPECIFICATION: GS-12-588 (PRELIMINARY)
- APPLICATION SPECIFICATION: GS-20-121 (PRELIMINARY)
- PRODUCT MARKING (PART NUMBER AND LOT CODE) ON THESE SURFACES.
- HOUSING MUST WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR-PHASE REFLOW OVEN.
- PACKAGING MEETS GS-14-920 LEAD-FREE LABELING SPECIFICATION.
- NOTCH INDICATES "ROW A" SIDE OF CONNECTOR.
- SEE APPLICATION SPECIFICATION FOR ROUTING GUIDELINES, ADDITIONAL PTH GUIDELINES, MATED DIMENSIONS, GUIDE PN SELECTION, ETC.
- SCREW IS OPTIONAL AND ENGAGES WITH BOTTOM OF GUIDE-PIN FROM BENEATH THE PCB FOR ADDITIONAL GUIDE-PIN SUPPORT.
- OPTIONAL HOLE LOCATION FOR GROUNDED PIN OR ADDITIONAL GUIDE-PIN SUPPORT. SEE TABLE 1 ON SHEET 1 FOR ADDITIONAL DETAILS.

REFER TABLE 3
FOR PTH, DRILL & PAD SIZES

	Ø 0.10	A	Y_BP	X_BP
---	--------	---	------	------



DETAIL A
SCALE 8:1

TABLE 3: PTH AND PAD SIZES WITH REFERENCE TO COMPLIANT PIN DRILL		
COMPLIANT PIN DRILL	PTH	PAD
Ø 0.55 [0.0217"]	Ø 0.45±0.05	Ø 0.85
Ø 0.45 [0.0177"]	Ø 0.35±0.05	Ø 0.75

PRELIMINARY



title	MODULE ASSEMBLY
vertical header, 8-column, 6-pair	
catalog no	SEE P/N TREE

dwg no	10104999	Rev.	2
CUSTOMER	sheet 8 of 8		